Tim Tilford

List of Publications by Year
in descending order

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		1684188	1720034
20	192	5	7
papers	citations	h-index	g-index

20	20	20	177
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Comparative Reliability of Inkjet-Printed Electronics Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 351-362.	2.5	9
2	Reliability Testing and Stress Measurement of QFN Packages Encapsulated by an Open-Ended Microwave Curing System. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 173-180.	2.5	6
3	Multi-Material Heatsink Design Using Level-Set Topology Optimization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1504-1513.	2.5	6
4	Design of Additively Manufactured Heatsinks for Power Electronics Thermal Management using Adjoint Level-set Topology Optimization. , 2019, , .		4
5	Numerical Analysis of the Design and Manufacture of Inkjet Printed Electronics Packaging. , 2018, , .		1
6	Design, manufacture and test for reliable 3D printed electronics packaging. Microelectronics Reliability, 2018, 85, 109-117.	1.7	20
7	Modelling Technologies and Applications. , 2018, , 45-82.		0
8	Multi-physics models and condition-based monitoring for 3D-Printing of electronic packages. , 2017, , .		5
9	Modelling methodologies for assessment of 3D inkjet-printed electronics. , 2016, , .		4
10	Predictive modelling for 3D inkjet printing processes. , 2016, , .		4
11	Data driven approach to quality assessment of 3D printed electronic products. , 2015, , .		21
12	Encapsulation of Microelectronic Components Using Open-Ended Microwave Oven. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 799-806.	2.5	10
13	Modelling and optimisation study on the fabrication of nanoâ€structures using imprint forming process. Engineering Computations, 2011, 28, 93-111.	1.4	2
14	Polymer cure modeling for microelectronics applications. , 2009, , .		9
15	Optimization of an Open-Ended Microwave Oven for Microelectronics Packaging. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 2635-2641.	4.6	10
16	Polymer Curing within an Optimised Open-Ended Microwave Oven. , 2008, , .		0
17	Predictive reliability and prognostics for electronic components: Current capabilities and future challenges. , 2008, , .		5
18	Wire Bond Reliability for Power Electronic Modules - Effect of Bonding Temperature. , 2007, , .		32

#	Article	IF	Citations
19	Thermal-mechanical Modelling of Power Electronic Module Packaging. , 2007, , .		3
20	Lifetime Prediction for Power Electronics Module Substrate Mount-down Solder Interconnect. , 2007, , .		41